

SPECIFICATIONS CLV54SR1C-70

OUTLINES DIMENSIONS

Description

*Oval Type

*Lens Color: Water Clear

*Without Flange

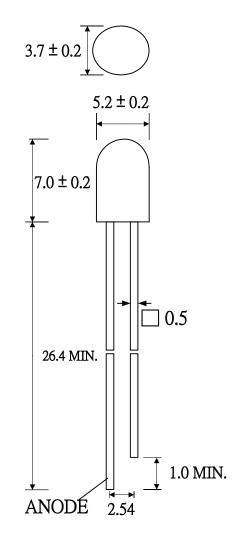
Features

*Emitted Color: Red

*High Luminous Intensity

*Technology: InGaAIP

*Peak Wavelength = 645nm



Notes:

- 1. All Dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLV54SR1C-70	InGaAlP	Red	Water Clear	70°/30°



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



ABSOLUTE MAXIMUM RATINGS

TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	Po	120	mW
Pulse Current Forward Current	IFP	100	mA
Continuous Forward Current	lF	50	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-40~+85	°C
Storage Temperature Range	Тѕтс	-40~+100	°C
I _{FP} = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5se			

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol Test Condition	Toot Condition	Value			l lait
Parameter		Min	Тур	Max	Unit	
Luminous Intensity	lv	I⊧ = 20mA	660	1000	ı	mcd
Forward Voltage	VF	I _F = 20mA	1	2.0	2.4	V
Reverse Leakage Current	lR	V _R = 5V	1	-	10	μΑ
Viewing Angle	201/2	I⊧ = 20mA	-	70/30	-	deg
Peak Wavelength	λP	I⊧ = 20mA	-	645	-	nm
Dominant Wavelength	λD	I⊧ = 20mA	-	635	-	nm
Spectral Line half-width	Δλ	I⊧ = 20mA	-	20	-	nm

^{*}Tolerance of viewing angle: -10 / +5 deg.

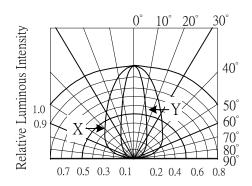


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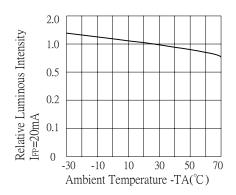


OPTICAL CHARACTERISTIC CURVES

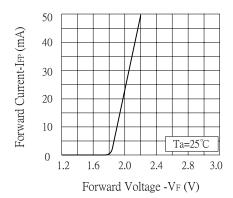
TYPICAL OPTICAL-ELECTRICAL CHARACTERISTIC CURVES



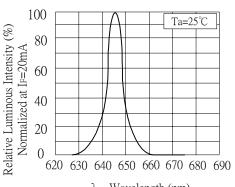
RADIATION DIAGRAM



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

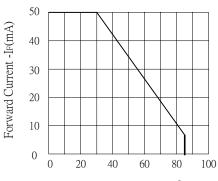


FORWARD CURRENT Vs. FORWARD VOLTAGE



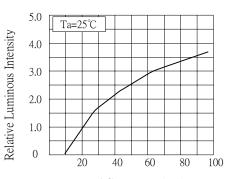
 λ - Wavelength (nm)

RELATIVE LUMINOUS INTENSITY Vs. WAVELENGTH



Ambient Temperature - $TA(^{\circ}C)$

MAX FORWARD CURRENT Vs. AMBIENT TEMPERATURE



Forward Current-IFP (mA)

LUMINOUS INTENSITY Vs. FORWARD CURRENT



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SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering				
Pre-Heat	100 °C Max			
Pre-Heat Time	60 Second Max			
Solder Bath Temperature	260 °C Max			
Dippng Time	5 Second Max			
Dipping Position	No lower than 3mm from the base of the epoxy			

Hand Soldering					
	3mm Series	Others			
Tomporature Soldering Time	300 °C Max	350 °C Max			
Temperature Soldering Time Position	3 Second Max	3 Second Max			
	No closer than 3mm from the	No closer than 3mm from the			
	base of the epoxy	base of the epoxy			

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

